





# Phase Control Thyristor Preliminary Information

DS5976-1.0 January 2011 (LN27909)

#### **FEATURES**

- Double Side Cooling
- High Surge Capability

#### **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

#### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>DRM</sub> and V <sub>RRM</sub> V	Conditions
DCR4590B28 DCR4590B26 DCR4590B24	2800 2600 2400	$\begin{split} T_{vj} &= \text{-}40^{\circ}\text{C to }125^{\circ}\text{C},\\ I_{DRM} &= I_{RRM} = 200\text{mA},\\ V_{DRM}, V_{RRM}t_p &= 10\text{ms},\\ V_{DSM}\&V_{RSM} &=\\ V_{DRM}\&V_{RRM} + 100V\\ respectively \end{split}$

Lower voltage grades available.

#### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

## DCR45900B28

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

## **KEY PARAMETERS**

$V_{DRM}$	2800V
$I_{T(AV)}$	4950A
I <sub>TSM</sub>	65000A
dV/dt*	2000V/µs
dl/dt	500A/μs
	<del>-</del>

## \* Higher dV/dt selections available

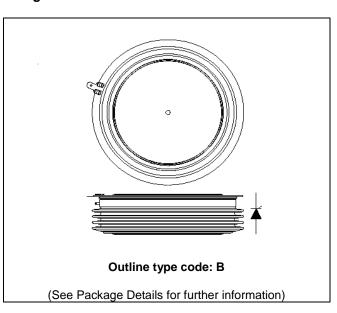


Fig. 1 Package outline





## **CURRENT RATINGS**

## $T_{\text{case}}$ = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Sid	de Cooled			
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	4590	А
I <sub>T(RMS)</sub>	RMS value	-	7210	А
lτ	Continuous (direct) on-state current	-	6180	А

## **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, T <sub>case</sub> = 125°C	65	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	21.13	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.007	°C/W
		Single side cooled	Anode DC	-	0.0116	°C/W
			Cathode DC	-	0.0181	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Clamping force 76kN	Double side	-	0.0014	°C/W
		(with mounting compound)	Single side	-	0.0028	°C/W
$T_{vj}$	Virtual junction temperature	Blocking V <sub>DRM</sub> / V <sub>RRM</sub>		-	125	°C
T <sub>stg</sub>	Storage temperature range			-55	125	°C
Fm	Clamping force			68.0	84.0	kN





# **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditio	ns	Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	200	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% $V_{DRM}$ , $T_j = 125$ °C, ga	ate open	-	2000	V/µs
dl/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 2x I <sub>T(AV)</sub>	Repetitive 50Hz	-	250	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	500	A/µs
		$t_r < 0.5 \mu s, T_j = 125 ^{\circ} C$				
$V_{T(TO)}$	Threshold voltage – Low level	500A to 3000A at T <sub>case</sub> = 125	5°C	-	0.78	V
	Threshold voltage – High level	3000A to 10000A at T <sub>case</sub> = 1	125°C	-	0.90	V
r <sub>T</sub>	On-state slope resistance – Low level	500A to 3000A at T <sub>case</sub> = 125°C		-	0.1371	mΩ
	On-state slope resistance – High level	3000A to 10000A at T <sub>case</sub> = 125°C		-	0.0957	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% V_{DRM}$ , gate source 30V, $10\Omega$			1.5	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j = 125$ °C, $V_R = 200$ V, $dI/dt = 1$ A/ $\mu$ s,			250	μs
		dV <sub>DR</sub> /dt = 20V/μs linear				
Qs	Stored charge	$I_T = 2000A$ , $T_j = 125$ °C, $dI/dt - 1A/\mu s$ ,		545	2030	μC
IL	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	Α
IH	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 50$	0A, I <sub>T</sub> = 5A	-	300	mA





#### **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
$V_{GT}$	Gate trigger voltage	V <sub>DRM</sub> = 5V, T <sub>case</sub> = 25°C	1.5	V
$V_{GD}$	Gate non-trigger voltage	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	0.4	V
I <sub>GT</sub>	Gate trigger current	V <sub>DRM</sub> = 5V, T <sub>case</sub> = 25°C	250	mA
I <sub>GD</sub>	Gate non-trigger current	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	10	mA

## **CURVES**

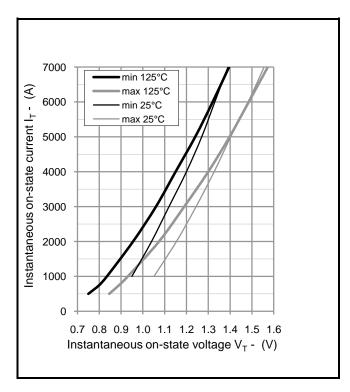


Fig.2 Maximum & minimum on-state characteristics

 $V_{TM} = A + BIn(I_T) + C.I_T + D.\sqrt{I_T}$ 

 $V_{TM}$  **EQUATION** Where A = 1.344406

B = - 0.153272 C = -0.000026

D = 0.021061

these values are valid for  $T_j = 125$ °C for  $I_T 500A to 10000A$ 

180

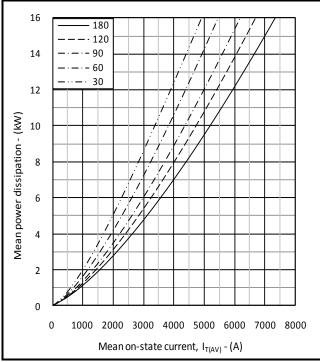
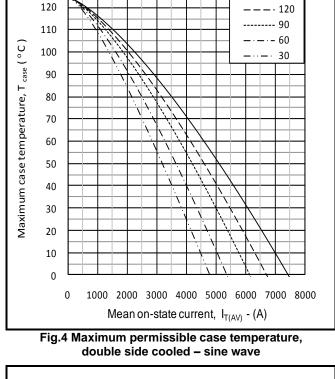


Fig.3 On-state power dissipation - sine wave



130

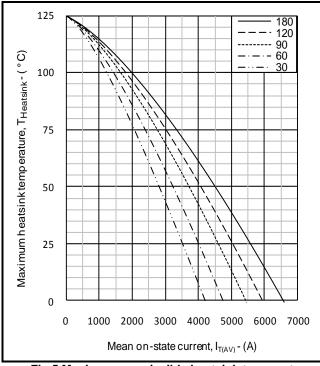


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

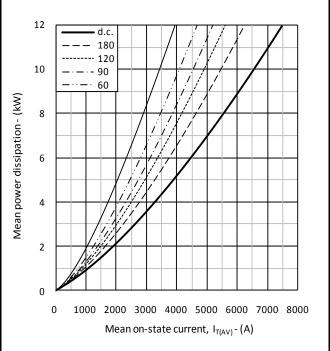


Fig.6 On-state power dissipation - rectangular wave



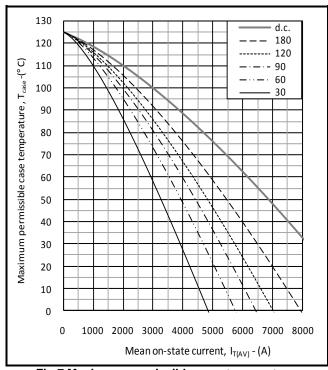


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

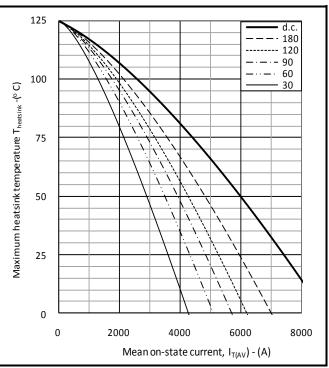
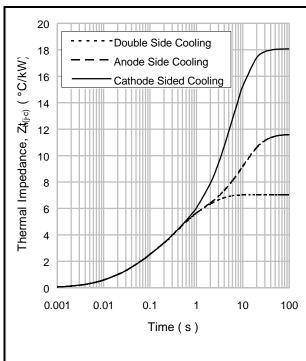


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave



		1	2	3	4
Double side cooled	R <sub>i</sub> (°C/kW)	0.502	1.333	2.9559	2.2335
	T <sub>i</sub> (s)	0.013708	0.054888	0.331193	1.6905
Anode side cooled	R <sub>i</sub> (°C/kW)	1.3035	3.138	1.1859	5.9136
	T <sub>i</sub> (s)	0.025107	0.241026	1.0806	11.002
Cathode side cooled	R <sub>i</sub> (°C/kW)	1.2616	2.6216	13.3603	0.8304
	T; (s)	0.024584	0.200504	5.7854	16.765

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(T/T_i))]$$

## ΔR<sub>th(i-c)</sub> Conduction

Tables show the increments of thermal resistance  $R_{\text{th(j-c)}}$  when the device operates at conduction angles other than d.c.

Double side cooling					
	$\Delta Z_{th}$ (z)				
$\theta$ °	sine.	rect.			
180	0.70	0.48			
120	0.80	0.68			
90	0.90	0.78			
60	1.00	0.89			
30	1.07	1.01			
15	1 10	1.07			

Al	node Side	Cooling	
	$\Delta Z_t$	<sub>h</sub> (z)	
θ°	sine.	rect.	
180	0.67	0.47	
120	0.77	0.66	
90	0.87	0.75	
60	0.95	0.86	
30	1.02	0.96	
15	1.05	1.02	

Cathode Sided Cooling				
	ΔZ	th (z)		
θ°	sine.	rect.		
180	0.67	0.47		
120	0.77	0.66		
90	0.87	0.76		
60	0.95	0.86		
30	1.02	0.96		
15	1.05	1.02		

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)

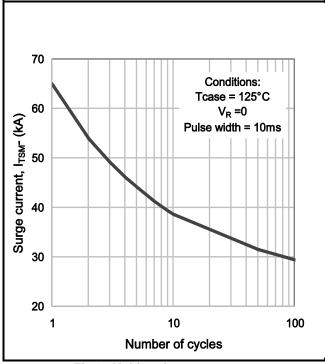


Fig.10 Multi-cycle surge current

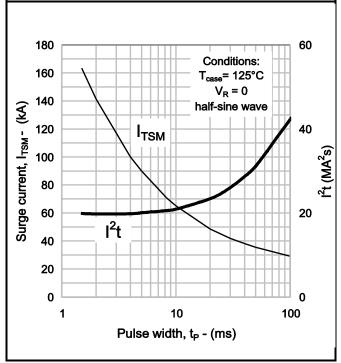


Fig.11 Single-cycle surge current

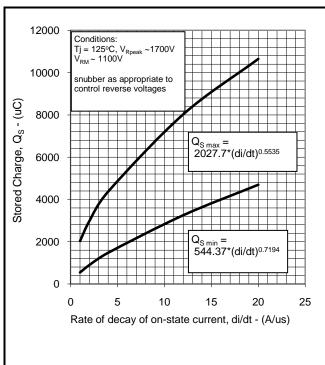


Fig.12 Stored charge

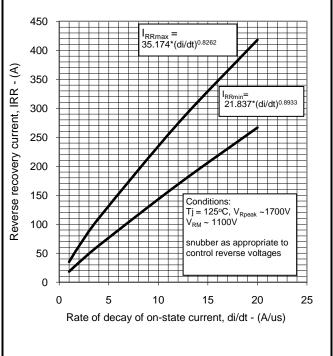


Fig.13 Reverse recovery current

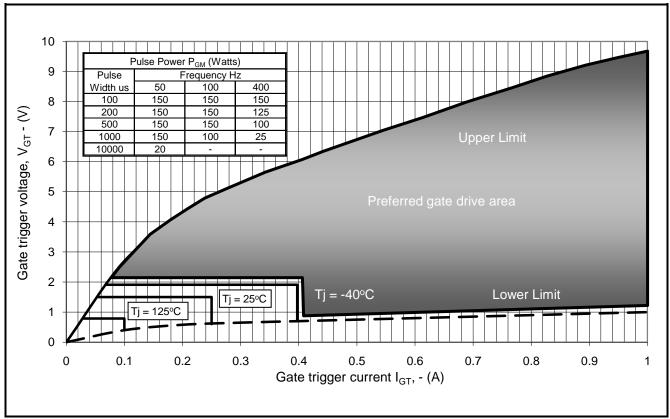


Fig14 Gate Characteristics

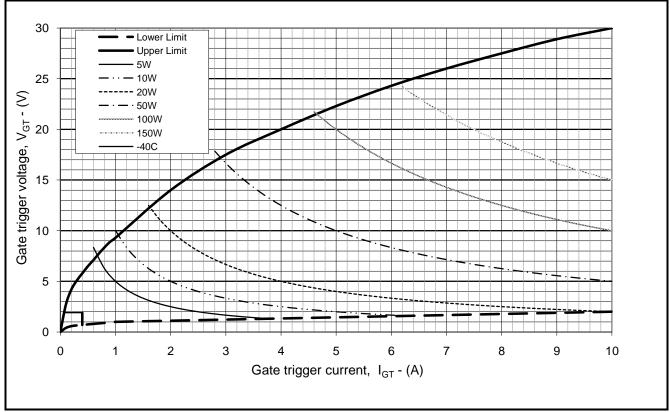


Fig. 15 Gate characteristics





#### **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

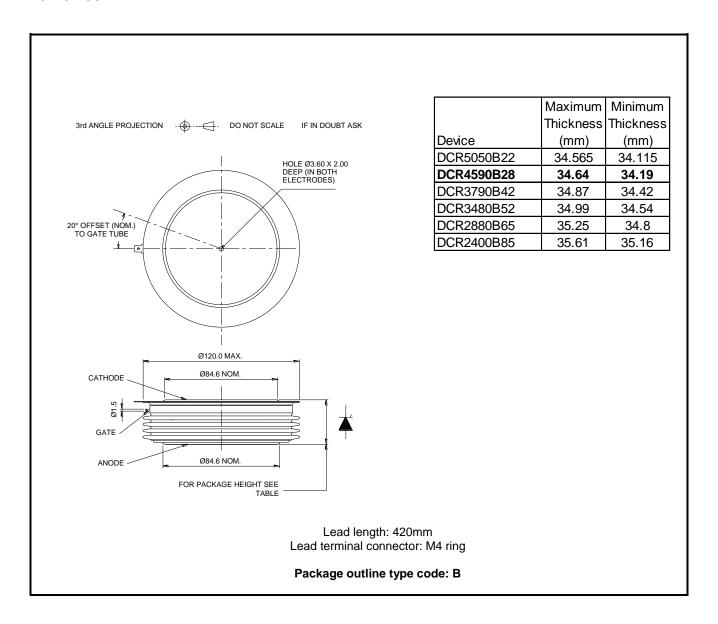


Fig.16 Package outline





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